

IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,
Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

IECQ Certificate of Approval Independent Testing Laboratory

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Integrated Service Technology (Shanghai) Co., Itd

No.455, Jinfeng Rd., Pudong new zone Shanghai China

The organization, facilities and procedures have been assessed and found to comply with the applicable requirements for Independent Testing Laboratory organization approval, in support of the IECQ system, which is in accordance with the Basic Rules IECQ 01 and Rules of Procedure IECQ 03-6 "Independent Testing Laboratory Assessment Program Requirements" of the IEC Quality Assessment System for Electronic Components (IECQ) and applicable requirements of ISO/IEC 17025: 2005 for the testing of electronic components under the IECQ.

Scope:

Environmental and Reliability Testing of Electronic Components, Assemblies, and Related Materials

See attached Schedule of Scope

-- Attached Schedule: IECQ-L DEKRA 17.0004-01-S Rev1.pdf --

Approved by Certification Body (CB): DEKRA Certification B.V.

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The validity of this certificate is maintained through on-going surveillance audits by the IECQ CB issuing this certificate.

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Schedule of Scope to Certificate of Approval

Independent Testing Laboratory
IECQ Certificate No.: IECQ-L DEKRA 17.0004-01

CB Certificate No.: DEKRA-C11B-001

Schedule Number: IECQ-L DEKRA 17.0004-01-S Rev No.: 1 Rev. Date: 2017/12/21 Page 1 of 1

1. Environmental and Reliability Testing of Electronic Components, Assemblies, and Related Materials

Description test	Standard	Remarks
Failure and material analysis of semiconductor IC, electronic components and PCB/PCBA includes FIB (Focused Ion Beam), SEM (Scanning electron microscope)	MIL-STD-883 Method 2018.4 JESD22A121 JESD201	Or customer specified test
Failure and material analysis of semiconductor IC, electronic components and PCB/PCBA, includes Electrical Analysis and Physical Analysis with Sample Preparation (Decap, X-section, etc)	MIL-STD-883 Method 2009.9 IPC-A-610; IPC-A-600 MIL-STD-883 Method 2008.4 JESD22A121; JESD201 IPC-TM-650 2.1.1; IPC-6012	Or customer specified test
Failure and material analysis of semiconductor IC, electronic components and PCB/PCBA, includes NDE (Non-destructive Testing)	MIL-STD-883 Method 2012.7 J-STD-035; J-STD-020	Or customer specified test
2nd level integration platform service. (Includes Pre-SMT/SMT / Temperature Cycling test /Thermal Shock test/ Drop test/ Shock test / Vibration test/ Bending test / gross leak test /dye &pry test /solderability test /Wire Bond Shear&Wire Bond Pull test / Physical Dimensions measurement /Solder Ball Shear test /Die Shear test)	Industrial (JESD 47) ,JESD-22-A104/IPC-9701/MIL-STD-883 /JESD22-A106/JESD22-B104/JESD22-B110/JESD22-B103/JEITA ED-4702/IPC-JEDEC-9702/IEC 60068-2-21-2006/SEMI G86-0303/AEC-Q200-003/005/IPC-610F/IPC-7525/JEDEC JESD22-B102/JEDEC JESD22-B100	Or customer specified test
Accelerated environment reliability stress tests (Includes Pre-condition / MSL / Accelerated Temperature-Humidity test / Temperature-Humidity with bias test / Temperature Cycling test / Power and temperature cycling test / Low Temperature storage test / Highly Accelerated Stress Test/Autoclave Test//Thermal Shock Test)	JESD 47,J-STD-020, JESD22-series;IEC-60068-series, MIL-STD-202/750/810/883,JESDJP001; EIA-364-32C, EIAJED-4701, AEC-Q100;AEC-Q101, AEC-Q200,	Or customer specified test
Accelerated lifetime simulation tests. (Includes Operating Life test / Early life failure rate test/ Endurance and Data retention test / Electro-Migration /Miscellaneous test)	JESD 47,JESD22-A108/A117, JESD61, MIL-STD-202/750/810/883, AEC- Q100;AEC-Q101, AEC-Q200,	Or customer specified test
Electrostatic discharge test. (Including : HBM / MM / CDM / Latch Up / ESD Gun)	JESD 47 ,JEDEC22-A114/A115/C101, EIA/JESD78, ANSI JEDEC ESDA JS001/JS002; AEC-Q100-002/003/004/011, AEC-Q101-001/002/005, AEC-Q200- 002,JEITA ED4701; IEC61000-4-2, MIL- STD-883	Or customer specified test

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